

ABSTRACT OF THE DISCLOSURE

A multi-chips stacked package at least comprises a substrate, an upper chip, a lower chip, a plurality of electrically conductive wires and a plurality of conductive bumps. The upper chip is flip-chip bonded to the upper surface of the substrate; and the lower chip is accommodated in the opening and wire-bonded to the upper chip. Furthermore, the lower chip can be wire-bonded to the substrate via a plurality of another electrically conductive wires, which directly connect the lower chip and the substrate.